



Printed Circuit Boards
Interconnection Carriers

PRINTED CIRCUIT BOARDS

01

17.02.2015

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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06 150 FR4 35 L20.18 P18_10_06

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_150_FR4_35_L20.18_p18_10_06

Layers	in μ	Material	Build-Up	Assembly		
Layer-1	35 μ	Copper		A1		
	60 μ	Prepreg			(60 μ PrePreg-Type: 1080)	
	100 μ	Prepreg			(100 μ PrePreg-Type: 2116)	
Layer-2	18 μ	Copper				
	200 μ	L-FR4			A2	
Layer-3	18 μ	Copper				
	180 μ	Prepreg				(180 μ PrePreg-Type: 7628)
	180 μ	Prepreg				
	180 μ	Prepreg				
Layer-4	100 μ	Prepreg				
	18 μ	Copper		B		
	200 μ	L-FR4				
Layer-5	18 μ	Copper				
	100 μ	Prepreg				
Layer-99	60 μ	Prepreg				
	35 μ	Copper				